

## TLYH190P(F)

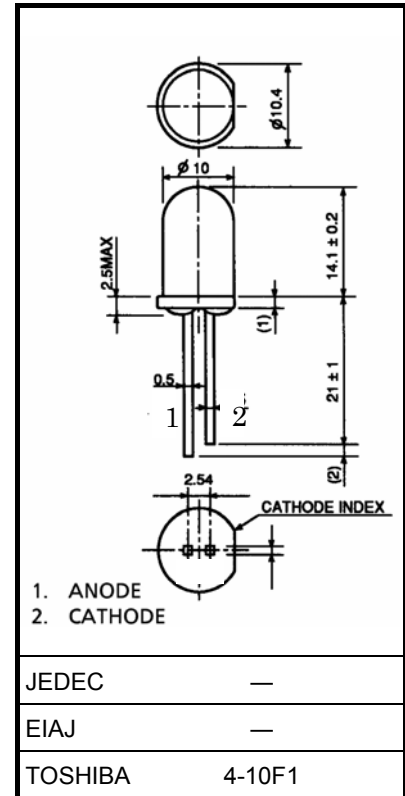
### Panel Circuit Indicator

- Lead(Pb)-free products (lead: Sn-Ag-Cu)
- 10 mm package
- InGaAlP technology
- All plastic mold type.
- Colorless clear lens
- Low drive current, high intensity yellow light emission  
Recommended forward current :  $I_F = 1 \sim 20$  mA (DC)
- All plastic molded lens, provides an excellent on-off contrast ratio.
- Fast response time, capable of pulse operation.
- High power luminous intensity
- Without stand-offs
- Applications: Suitable for outdoor message signboard, safety equipment.

### Maximum Ratings ( $T_a = 25^\circ\text{C}$ )

Characteristic	Symbol	Rating	Unit
Forward current (DC)	$I_F$	50	mA
Reverse voltage	$V_R$	4	V
Power dissipation	$P_D$	125	mW
Operating temperature range	$T_{opr}$	-30~85	$^\circ\text{C}$
Storage temperature range	$T_{stg}$	-40~120	$^\circ\text{C}$

Unit in mm



Weight: 1.0 g



For part availability and ordering information please call Toll Free: 800.984.5337  
Website: [www.marktechopto.com](http://www.marktechopto.com) | Email: [info@marktechopto.com](mailto:info@marktechopto.com)

## Electrical And Optical Characteristics (Ta = 25°C)

Characteristic		Symbol	Test Condition	Min	Typ.	Max	Unit
Forward voltage		$V_F$	$I_F = 20\text{mA}$	—	2.1	2.5	V
Reverse current		$I_R$	$V_R = 4\text{V}$	—	—	50	$\mu\text{A}$
Luminous intensity	TLYH190P(F)	$I_V$	$I_F = 20\text{mA}$ (Note)	8500	30000	—	mcd
	TLYH190P (XY,F)			15300	—	73600	
Peak emission wavelength		$\lambda_P$	$I_F = 20\text{mA}$	—	(590)	—	nm
Spectral line half width		$\Delta\lambda$	$I_F = 20\text{mA}$	—	13	—	nm
Dominant wavelength		$\lambda_d$	$I_F = 20\text{mA}$	—	587	—	nm

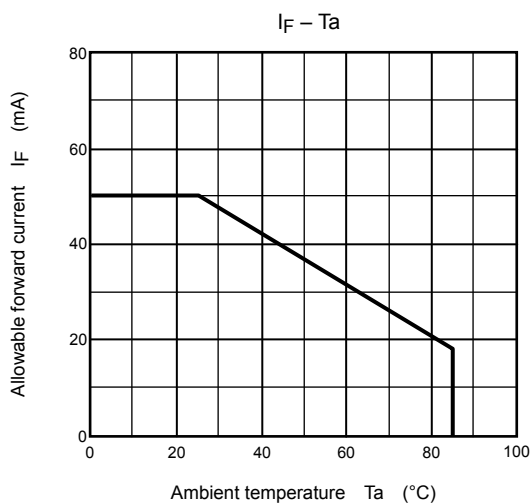
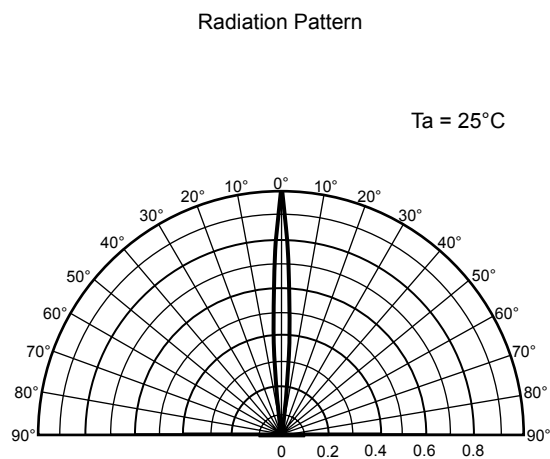
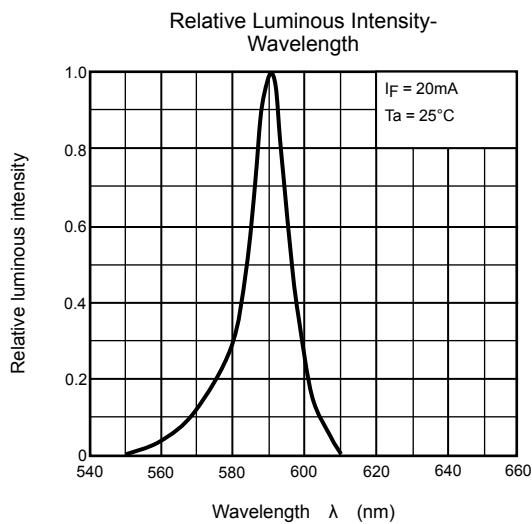
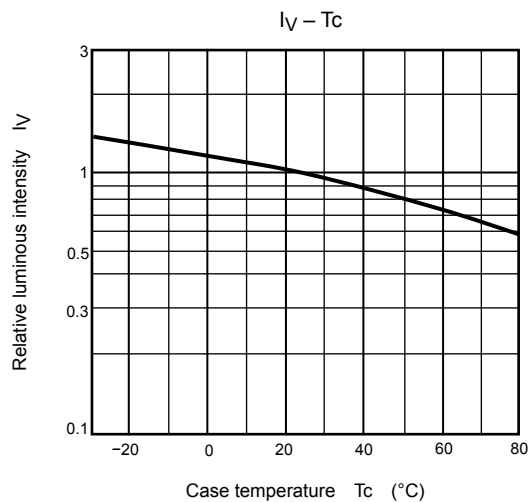
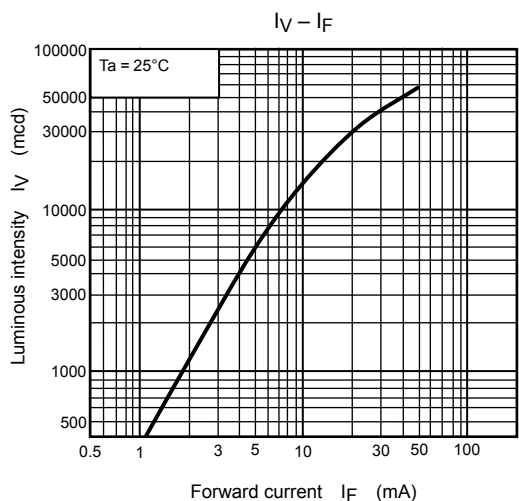
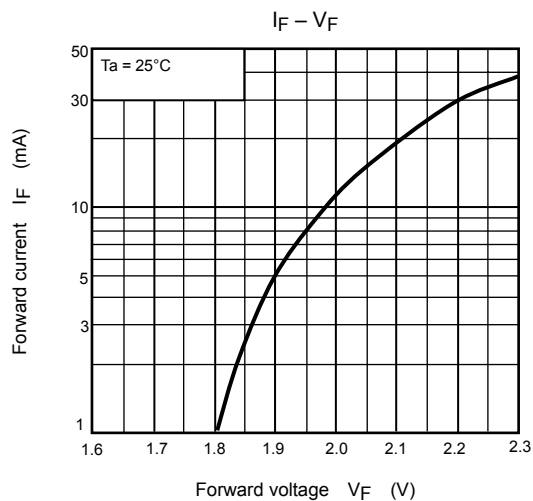
(Note): Lamps are classified into the following ranks according to their luminous intensity , and packed in boxes by each rank .

W: 8500 - 2300mcd, X: 15300 - 41400mcd, Y: 27200mcd -

## Precaution

Please be careful of the followings

- Soldering temperature : 260°C max      Soldering time : 3s max  
(Soldering portion of lead: up to 1.6mm from the body of the device)
- If the lead is formed, the lead should be formed up to 1.6mm from the body of the device without forming stress to the resin. Soldering should be performed after lead forming.
- This visible LED lamp also emits some IR light. If a photodetector is located near the LED lamp, please ensure that it will not be affected by this IR light.



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